



- Active
 - L1: (26490) (polish\$ or CMP) with (clean\$ or remove\$ or rinse\$)
 - L2: (8387) (clean\$ or remove\$ or rinse\$) with (H2O2 or hydrogenperoxide or "H.sub.2O.sub.2" or "H...
 - L3: (188) 1 with 2
 - L4: (2978218) @ad<19991231
 - L5: (93) 3 and 4
 - L6: (1) ("6617205").PN.
 - L7: (5419) (clean\$ or rinse\$) with (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen...
 - L8: (0) 6 and 7
 - L9: (9807) (clean\$ or rinse\$) same (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen...
 - L10: (0) 6 and 9
 - L11: (35034) (clean\$ or rinse\$) and (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydroge...
 - L12: (1) 6 and 11
 - L13: (0) "cleaning while polishing" or "rinsing while polishing"
 - L14: (0) "cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing"
 - L15: (0) 2 and 14
 - L16: (0) 9 and 14
 - L17: (0) 11 and 14
 - L18: (86073) H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O...
 - L19: (0) 14 and 18
 - L20: (3) 1 and 14
- Failed
- Saved

USPAT, US IP: Purvis

Default operator: Highlight all hit terms initially

"cleaning while polishing" or
 "rinsing while polishing" or
 "cleaning during polishing" or
 "rinsing during polishing"

Buttons: Add term, Add term, Links, Text, HTML

Document	Issue Da	Page	Title	Current	Current X	Retrieval	Inventor	SCP

L Number	Hits	Search Text	DB	Time stamp
1	26490	(polish\$ or CMP) with (clean\$ or remove\$ or rinse\$)	USPAT; US-PGPUB	2004/03/10 09:35
2	8387	(clean\$ or remove\$ or rinse\$) with (H2O2 or hydrogenperoxide or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2" or "hydrogen peroxide" or "hydrogen-peroxide")	USPAT; US-PGPUB	2004/03/10 09:33
3	188	((polish\$ or CMP) with (clean\$ or remove\$ or rinse\$)) with ((clean\$ or remove\$ or rinse\$) with (H2O2 or hydrogenperoxide or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2" or "hydrogen peroxide" or "hydrogen-peroxide"))	USPAT; US-PGPUB	2004/03/10 08:53
4	2978218	@ad<19991231	USPAT; US-PGPUB	2004/03/10 08:54
5	93	((((polish\$ or CMP) with (clean\$ or remove\$ or rinse\$)) with ((clean\$ or remove\$ or rinse\$) with (H2O2 or hydrogenperoxide or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2" or "hydrogen peroxide" or "hydrogen-peroxide")))) and @ad<19991231	USPAT; US-PGPUB	2004/03/10 09:02
6	1	("6617205").PN.	USPAT; US-PGPUB	2004/03/10 09:03
7	5419	(clean\$ or rinse\$) with (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")	USPAT; US-PGPUB	2004/03/10 09:33
8	0	((("6617205").PN.) and ((clean\$ or rinse\$) with (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")))	USPAT; US-PGPUB	2004/03/10 09:04
9	9807	(clean\$ or rinse\$) same (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")	USPAT; US-PGPUB	2004/03/10 09:34
10	0	((("6617205").PN.) and ((clean\$ or rinse\$) same (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")))	USPAT; US-PGPUB	2004/03/10 09:04
11	35034	(clean\$ or rinse\$) and (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")	USPAT; US-PGPUB	2004/03/10 09:35
12	1	((("6617205").PN.) and ((clean\$ or rinse\$) and (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")))	USPAT; US-PGPUB	2004/03/10 09:05
13	0	"cleaning while polishing" or "rinsing while polishing"	USPAT; US-PGPUB	2004/03/10 09:30
14	3	"cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing" or "rinsing during polishing"	USPAT; US-PGPUB	2004/03/10 09:31

15	0	((clean\$ or remove\$ or rinse\$) with (H2O2 or hydrogenperoxide or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2" or "hydrogen peroxide" or "hydrogen-peroxide")) and ("cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing" or "rinsing during polishing")	USPAT; US-PGPUB	2004/03/10 09:33
16	0	((clean\$ or rinse\$) same (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")) and ("cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing" or "rinsing during polishing")	USPAT; US-PGPUB	2004/03/10 09:34
17	0	((clean\$ or rinse\$) and (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")) and ("cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing" or "rinsing during polishing")	USPAT; US-PGPUB	2004/03/10 09:34
18	86073	H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2"	USPAT; US-PGPUB	2004/03/10 09:35
19	0	("cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing" or "rinsing during polishing") and (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2 O.sub.2")	USPAT; US-PGPUB	2004/03/10 09:35
20	3	((polish\$ or CMP) with (clean\$ or remove\$ or rinse\$)) and ("cleaning while polishing" or "rinsing while polishing" or "cleaning during polishing" or "rinsing during polishing")	USPAT; US-PGPUB	2004/03/10 09:35

EAST - [defaultmine.wsp1]

Drafts
 Pending
 Active
 L1: (13911) (rins\$ with (polish\$ or CMP)) or (clean\$ with (polish\$ or CMP))
 L2: (1382816) metal or metals
 L3: (1196) 1 with 2
 L4: (75363) +38\$7.ccls.
 L5: (213) 3 and 4
 L6: (2978218) @ad<19991231
 L7: (76) 5 and 6
 L8: (86073) H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O...
 Failed
 Saved
 Favorites
 Tagged (0)
 UDC
 Queuc
 Trash

Search:
 DBs: USPAT1 Dupals
 Default operator: Highlight all hit terms initially

	U	I	Document	Issue Da	Page	Title	Current	Current X	Retrieval	Inventor	S	C	P	2	3	▲
1	<input type="checkbox"/>	<input type="checkbox"/>	US 200100	20011101	17	SEMICONDUCTO	+38/643	458/643		YOKOI, NAOKI	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	<input type="checkbox"/>	US 663916	2003102	16	Chemical/mechanical polishi	216/88	216/100		Small, Robert J. et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	<input type="checkbox"/>	US 629100	20010101	16	METHOD OF CLF	228/607	228/607		Yokoi, Naoki	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

L Number	Hits	Search Text	DB	Time stamp
1	13911	(rins\$ with (polish\$ or CMP)) or (clean\$ with (polish\$ or CMP))	USPAT; US-PGPUB	2004/03/10 17:53
2	1382816	metal or metals	USPAT; US-PGPUB	2004/03/10 17:53
3	1196	((rins\$ with (polish\$ or CMP)) or (clean\$ with (polish\$ or CMP))) with (metal or metals)	USPAT; US-PGPUB	2004/03/10 17:54
4	75363	438\$7.ccls.	USPAT; US-PGPUB	2004/03/10 17:54
5	213	((((rins\$ with (polish\$ or CMP)) or (clean\$ with (polish\$ or CMP))) with (metal or metals)) and 438\$7.ccls.	USPAT; US-PGPUB	2004/03/10 17:54
6	2978218	@ad<19991231	USPAT; US-PGPUB	2004/03/10 17:55
7	76	(((((rins\$ with (polish\$ or CMP)) or (clean\$ with (polish\$ or CMP))) with (metal or metals)) and 438\$7.ccls.) and @ad<19991231	USPAT; US-PGPUB	2004/03/10 17:58
8	86073	H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2O.sub.2"	USPAT; US-PGPUB	2004/03/10 17:59
9	31	(((((rins\$ with (polish\$ or CMP)) or (clean\$ with (polish\$ or CMP))) with (metal or metals)) and 438\$7.ccls.) and @ad<19991231) and (H2O2 or hydrogenperoxide or "hydrogen peroxide" or "hydrogen-peroxide" or "H.sub.2O.sub.2" or "H.sub.2O.sub.2")	USPAT; US-PGPUB	2004/03/10 17:59

- ☐ Drafts
- ☐ Pending
- ☐ Active
 - ☐ L1: (75478) 438/\$.ccls.
 - ☐ L2: (536100) semiconductor or ic or "integrated circuit" or microelectronic
 - ☐ L3: (1) ("6555401").PN.
 - ☐ L4: (135502) polish\$3
 - ☐ L5: (134806) rins\$3
 - ☐ L6: (2045) polish\$3 with rins\$3
 - ☐ L7: (536100) semiconductor or ic or "integrated circuit" or microelectronic
 - ☐ L8: (1083) (polish\$3 with rins\$3) and (semiconductor or ic or "integrated circuit" or microelect...
 - ☐ L9: (636181) gradual or gradually or transition
 - ☐ L10: (38) (polish\$3 with rins\$3) with (gradual or gradually or transition)
 - ☐ L11: (3) (semiconductor or ic or "integrated circuit" or microelectronic) and (polish\$3 with
- ☐ Failed
- ☐ Saved
- ☐ Favorites
- ☐ Tagged (0)
- ☐ UDC
- ☐ Queue
- ☐ Trash

USPAT. (3) Polish

Default operator: Highlight all to terms initially

(semiconductor or ic or "integrated circuit" or microelectronic) and ((polish\$3 with rins\$3) with (gradual or gradually or transition))

Buttons: Search, Browse, Query, Help, Print, Home

	U1	Documen	Issue D	Page	Title	Current	Current	Retriev	Inventor	SCP	Image D	P
1	F	US 2002	200211	13	Method for finishing po	438/692	438/693		Walitzki, Hans S	F	F	US 200
2	F	US 2002	200209	17	Vertically configured c	204/224	204/297		Velodarsky, Kon	F	F	US 200
3	F	US 2002	200207	12	SEAL FOR USE	431/237			Yednak, Andrew	F	F	US 200